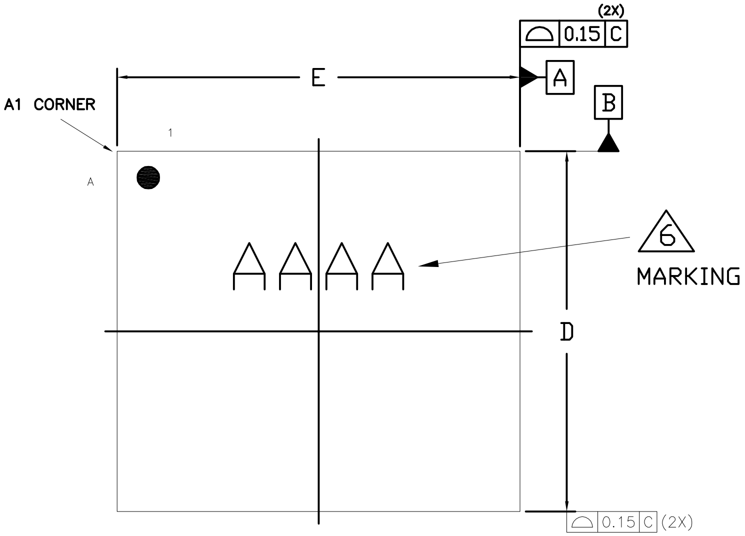
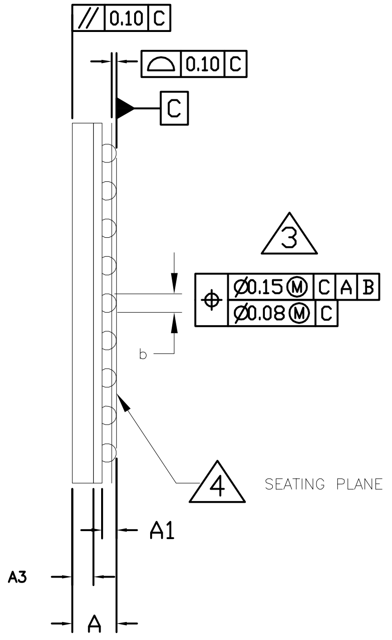
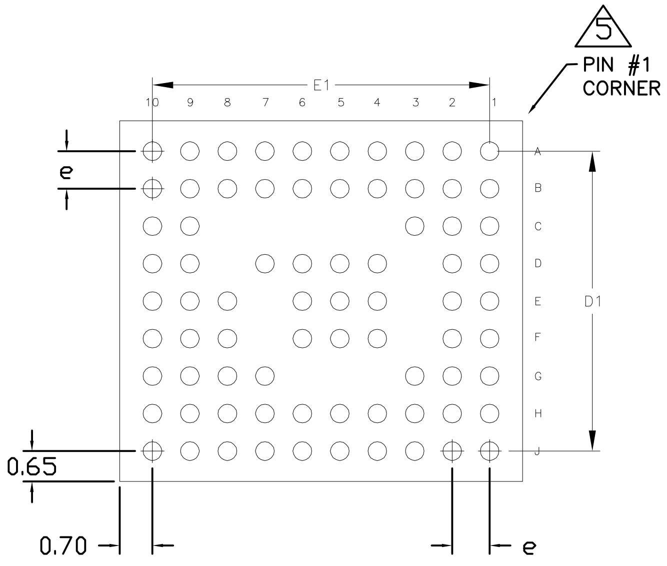


TOP VIEW



SIDE VIEW



BOTTOM VIEW

DIMENSIONS			
REF.	MIN.	NOM.	MAX.
A			1.04
A1	0.21	0.31	0.41
A3	0.45±0.05		
D	7.70		
D1	6.4 BSC		
E	8.60		
E1	7.20 BSC		
b	0.40±0.05		
e	0.80 BSC		
N	76		
PKG. CODE: X767A8F+1 X767A8F+2			

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS
5. A1 BALL PAD CORNER I.D.
6. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY

-DRAWING NOT TO SCALE-

maxim
integrated™

TITLE:
PACKAGE OUTLINE, 76 BALLS
FLIP CHIP CSP, 7.7x8.6x1.04 MM

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-0733	B	1/1